

MC10EL58, MC100EL58

5.0 V ECL 2:1 Multiplexer

Description

The MC10EL/100EL58 is a 2:1 multiplexer. The device is functionally equivalent to the E158 device with higher performance capabilities. With propagation delays and output transition times significantly faster than the E158, the EL58 is ideally suited for those applications which require the ultimate in AC performance.

The 100 Series contains temperature compensation.

Features

- 230 ps Propagation Delay
- PECL Mode Operating Range: $V_{CC} = 4.2\text{ V to }5.7\text{ V}$ with $V_{EE} = 0\text{ V}$
- NECL Mode Operating Range: $V_{CC} = 0\text{ V}$ with $V_{EE} = -4.2\text{ V to }-5.7\text{ V}$
- Internal Input Pulldown Resistors on D_a , D_b , and SEL
- Pb-Free Packages are Available

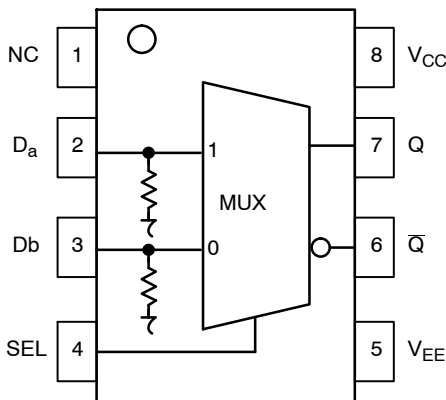


Figure 1. Logic Diagram and Pin Assignment



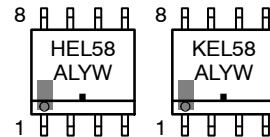
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<http://onsemi.com>

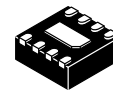
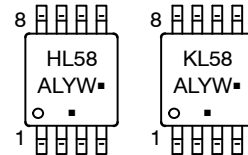
MARKING DIAGRAMS*



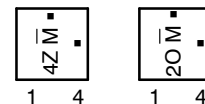
**SOIC-8
D SUFFIX
CASE 751**



**TSSOP-8
DT SUFFIX
CASE 948R**



**DFN8
MN SUFFIX
CASE 506AA**



H = MC10	L = Wafer Lot
K = MC100	Y = Year
4Z = MC10	W = Work Week
2O = MC100	M̄ = Date Code
A = Assembly Location	▪ = Pb-Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

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Table 1. PIN DESCRIPTION

PIN	FUNCTION
D _a , D _b	ECL Data Inputs
Q, Q̄	ECL Data Outputs
SEL	ECL Select Input
V _{CC}	Positive Supply
V _{EE}	Negative Supply
NC	No Connect
EP	(DFN8 only) Thermal exposed pad must be connected to a sufficient thermal conduit. Electrically connect to the most negative supply (GND) or leave unconnected, floating open.

Table 2. FUNCTION TABLE

SEL*	Data
H	a
L	b

* Pin will default low when left open.

Table 3. ATTRIBUTES

Characteristics	Value
Internal Input Pulldown Resistor	75 kΩ
Internal Input Pullup Resistor	N/A
ESD Protection	Human Body Model Machine Model
	> 1 kV > 100 V
Moisture Sensitivity, Indefinite Time Out of Drypack (Note 1)	Level 1
Flammability Rating	Oxygen Index: 28 to 34
	UL 94 V-0 @ 0.125 in
Transistor Count	45
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test	

1. Refer to Application Note AND8003/D for additional information.

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Table 4. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	PECL Mode Power Supply	V _{EE} = 0 V		8	V
V _{EE}	NECL Mode Power Supply	V _{CC} = 0 V		-8	V
V _I	PECL Mode Input Voltage NECL Mode Input Voltage	V _{EE} = 0 V	V _I ≤ V _{CC}	6	V
		V _{CC} = 0 V	V _I ≥ V _{EE}	-6	V
I _{out}	Output Current	Continuous Surge		50	mA
				100	mA
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ _{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm	SOIC-8	190	°C/W
		500 lfpm	SOIC-8	130	°C/W
θ _{JC}	Thermal Resistance (Junction-to-Case)		SOIC-8	41 to 44	°C/W
θ _{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm	TSSOP-8	185	°C/W
		500 lfpm	TSSOP-8	140	°C/W
θ _{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	TSSOP-8	41 to 44	°C/W
θ _{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm	DFN8	129	°C/W
		500 lfpm	DFN8	84	°C/W
T _{sol}	Wave Solder	Pb Pb-Free	<2 to 3 sec @ 248°C <2 to 3 sec @ 260°C	265	°C
				265	°C
θ _{JC}	Thermal Resistance (Junction-to-Case)	(Note 2)	DFN8	35 to 40	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

2. JEDEC standard multilayer board – 2S2P (2 signal, 2 power)

Table 5. 10EL SERIES PECL DC CHARACTERISTICS V_{CC}= 5.0 V; V_{EE}= 0.0 V (Note 3)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I _{EE}	Power Supply Current		14	17		14	17		14	17	mA
V _{OH}	Output HIGH Voltage (Note 4)	3920	4010	4110	4020	4105	4190	4090	4185	4280	mV
V _{OL}	Output LOW Voltage (Note 4)	3050	3200	3350	3050	3210	3370	3050	3227	3405	mV
V _{IH}	Input HIGH Voltage	3770		4110	3870		4190	3940		4280	mV
V _{IL}	Input LOW Voltage	3050		3500	3050		3520	3050		3555	mV
I _{IH}	Input HIGH Current			150			150			150	μA
I _{IL}	Input LOW Current	0.5			0.5			0.3			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

3. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +0.06 V / -0.5 V.

4. Outputs are terminated through a 50 ohm resistor to V_{CC}-2 volts.

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Table 6. 10EL SERIES NECL DC CHARACTERISTICS $V_{CC}= 0.0\text{ V}$; $V_{EE}= -5.0\text{ V}$ (Note 5)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		14	17		14	17		14	17	mA
V_{OH}	Output HIGH Voltage (Note 6)	-1080	-990	-890	-980	-895	-810	-910	-815	-720	mV
V_{OL}	Output LOW Voltage (Note 6)	-1950	-1800	-1650	-1950	-1790	-1630	-1950	-1773	-1595	mV
V_{IH}	Input HIGH Voltage	-1230		-890	-1130		-810	-1060		-720	mV
V_{IL}	Input LOW Voltage	-1950		-1500	-1950		-1480	-1950		-1445	mV
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.3			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

5. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +0.06 V / -0.5 V.

6. Outputs are terminated through a 50 ohm resistor to $V_{CC}-2$ volts.

Table 7. 100EL SERIES PECL DC CHARACTERISTICS $V_{CC}= 5.0\text{ V}$; $V_{EE}= 0.0\text{ V}$ (Note 7)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		14	17		14	17		16	19	mA
V_{OH}	Output HIGH Voltage (Note 8)	3915	3995	4120	3975	4045	4120	3975	4050	4120	mV
V_{OL}	Output LOW Voltage (Note 8)	3170	3305	3445	3190	3295	3380	3190	3295	3380	mV
V_{IH}	Input HIGH Voltage	3835		4120	3835		4120	3835		4120	mV
V_{IL}	Input LOW Voltage	3190		3525	3190		3525	3190		3525	mV
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

7. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +0.8 V / -0.5 V.

8. Outputs are terminated through a 50 ohm resistor to $V_{CC}-2$ volts.

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Table 8. 100EL SERIES NECL DC CHARACTERISTICS $V_{CC}= 0.0\text{ V}$; $V_{EE}= -5.0\text{ V}$ (Note 9)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		14	17		14	17		16	19	mA
V_{OH}	Output HIGH Voltage (Note 10)	-1085	-1005	-880	-1025	-955	-880	-1025	-955	-880	mV
V_{OL}	Output LOW Voltage (Note 10)	-1830	-1695	-1555	-1810	-1705	-1620	-1810	-1705	-1620	mV
V_{IH}	Input HIGH Voltage	-1165		-880	-1165		-880	-1165		-880	mV
V_{IL}	Input LOW Voltage	-1810		-1475	-1810		-1475	-1810		-1475	mV
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

9. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +0.8 V / -0.5 V.

10. Outputs are terminated through a 50 ohm resistor to $V_{CC}-2$ volts.

Table 9. AC CHARACTERISTICS $V_{CC}= 5.0\text{ V}$; $V_{EE}= 0.0\text{ V}$ or $V_{CC}= 0.0\text{ V}$; $V_{EE}= -5.0\text{ V}$ (Note 11)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f_{max}	Maximum Toggle Frequency					1.5					GHz
t_{PLH} t_{PHL}	Propagation Delay to Output D to Q SEL to Q	60 90	220 250	380 410	120 150	230 260	340 370	140 170	250 280	360 390	ps
t_{JITTER}	Random Clock Jitter (RMS)					0.9					ps
t_r t_f	Output Rise/Fall Times Q (20% - 80%)	100	225	350	100	225	350	100	225	350	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

11. 10 Series: V_{EE} can vary +0.06 V / -0.5 V.

100 Series: V_{EE} can vary +0.8 V / -0.5 V.

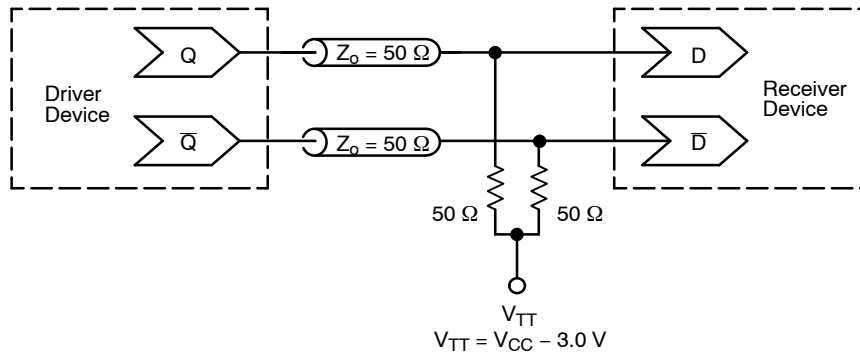


Figure 2. Typical Termination for Output Driver and Device Evaluation
(See Application Note AND8020/D – Termination of ECL Logic Devices.)

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ORDERING INFORMATION

Device	Package	Shipping [†]
MC10EL58D	SOIC-8	98 Units / Rail
MC10EL58DG	SOIC-8 (Pb-Free)	98 Units / Rail
MC10EL58DR2	SOIC-8	2500 / Tape & Reel
MC10EL58DR2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel
MC10EL58DT	TSSOP-8	100 Units / Rail
MC10EL58DTG	TSSOP-8 (Pb-Free)	100 Units / Rail
MC10EL58DTR2	TSSOP-8	2500 / Tape & Reel
MC10EL58DTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel
MC10EL58MNR4	DFN8	1000 / Tape & Reel
MC10EL58MNR4G	DFN8 (Pb-Free)	1000 / Tape & Reel
MC100EL58D	SOIC-8	98 Units / Rail
MC100EL58DG	SOIC-8 (Pb-Free)	98 Units / Rail
MC100EL58DR2	SOIC-8	2500 / Tape & Reel
MC100EL58DR2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel
MC100EL58DT	TSSOP-8	100 Units / Rail
MC100EL58DTG	TSSOP-8 (Pb-Free)	100 Units / Rail
MC100EL58DTR2	TSSOP-8	2500 / Tape & Reel
MC100EL58DTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel
MC100EL58MNR4	DFN8	1000 / Tape & Reel
MC100EL58MNR4G	DFN8 (Pb-Free)	1000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

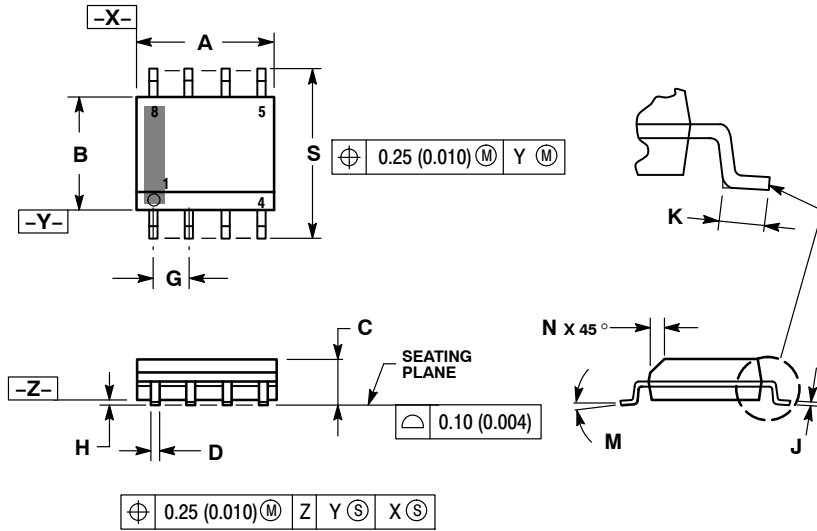
Resource Reference of Application Notes

- AN1405/D** – ECL Clock Distribution Techniques
- AN1406/D** – Designing with PECL (ECL at +5.0 V)
- AN1503/D** – ECLinPS™ I/O SPICE Modeling Kit
- AN1504/D** – Metastability and the ECLinPS Family
- AN1568/D** – Interfacing Between LVDS and ECL
- AN1672/D** – The ECL Translator Guide
- AND8001/D** – Odd Number Counters Design
- AND8002/D** – Marking and Date Codes
- AND8020/D** – Termination of ECL Logic Devices
- AND8066/D** – Interfacing with ECLinPS
- AND8090/D** – AC Characteristics of ECL Devices

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PACKAGE DIMENSIONS

SOIC-8 NB
CASE 751-07
ISSUE AH

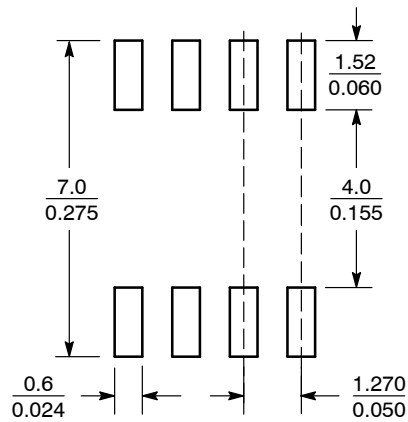


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0°	8°	0°	8°
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

SOLDERING FOOTPRINT*



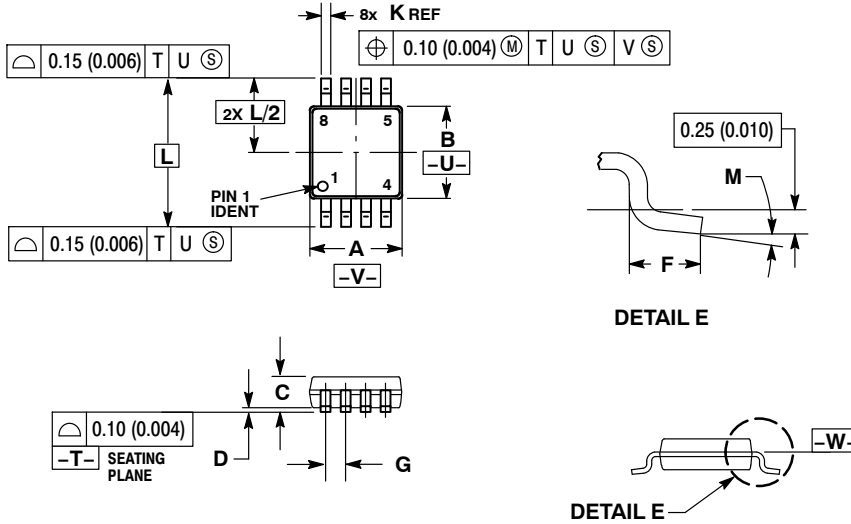
SCALE 6:1 $\left(\frac{\text{mm}}{\text{inches}}\right)$

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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PACKAGE DIMENSIONS

TSSOP-8
DT SUFFIX
PLASTIC TSSOP PACKAGE
CASE 948R-02
ISSUE A



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	2.90	3.10	0.114	0.122
C	0.80	1.10	0.031	0.043
D	0.05	0.15	0.002	0.006
F	0.40	0.70	0.016	0.028
G	0.65 BSC		0.026 BSC	
K	0.25	0.40	0.010	0.016
L	4.90 BSC		0.193 BSC	
M	0°	6°	0°	6°

